Type: XT1900GI
Expiry date: No date

Configuration Items:

board configuration	OADB
AA processing rack	MPCR2 processing rack
Communication with Air Control Cabinet	RS232 communication
Version of the Air Control Cabinet (ACC)	ACC MK 1 to 4
Automatic CUA	Absent
Automatic CUA exchanger architecture	Adjacent to the Rema objective
DOEs in lower disk ADE	Not Applicable
TIS plate deformation correction	Enabled
Functional use of Active Elements	BALE function as BALE
Air Gauge Improved Levelling	AGILE1
PDOC quality indicator check	PDOC quality indicator functionality is absent
Activation of the airknife during hovering	Airknife enabled during hovering in wet mode
ALE 1 Use	Calibration
Light source selection, for FIR laser	Light source selection undefined
Light source selection, for green laser	Light source selection undefined
Light source selection, for NIR laser	Light source selection undefined
Light source selection, for red laser	Light source selection undefined
Alignment Sensor Type	Athena Narrow Marks OM
Alignment Settle Time	Basic
Alignment Recipe Override	Alignment Recipe Override Disabled
Alignment Strategy ID Standard or Extended. Protected.	Alignment Strategy ID max length is 15 characters
Avoid I1 or I2 mark on TIS plates	Disabled;
Alignment Camera Mirror	Absent
Alignment laser configuration	2 color laser
Indication what kind of AM controller hardware is present	DICR
APACE used in production.	APACE is disabled in production.
Active Pupil Aberration Correction lens Element	Metrology does not use any APACE
Active Pupil Aberration Correction Element type	APACE Absent
Control the APCAP miscapture recovery	The APCAP miscapture recovery is disabled
Automatic PCE exchanger	Present
Application Type	Scanner Application
Defines the type of data that is restored	Restore settings and calibration data
routing for ASML test purposes	Disabled
Assure System Snapshots	Assure System Snapshots not allowed
Ast offset correction in TIS LHFB/LOCO (Version 3)	Disabled
Allow even orders usage	Absent
Athena Focus Improvements 1	Present
The exposure field size to be used during the TPT test	Narrow Field size
Attenuator Mirror Type	Quartz Attenuator Mirror
The type of Attenuator	Variable
Automated Lens Heating Calibration	Enabled
Automated DOE Exchanger	Present
Automated DOE Exchanger Architecture	16 slots
Backup method for machine data	Legacy, using asml_backup_settings
Automated Reticle Transport System	Absent
Choice of avoidance routing.	Phase 2
Avoid Track INPUT/OUTPUT conflicts, Raise AS after APR	Avoid Track INPUT/OUTPUT conflicts disabled
BALE Type	Piezo Valves
BaseLiner focus control.	BaseLiner-Focus application is enabled.
BaseLiner focus high order intrafield	BaseLiner-Focus high order intrafield is disabled.
BaseLiner overlay control.	BaseLiner-Overlay application is enabled.

BA-XY Reticle preference: V1 or V2; default is V2	V1 BA-XY Reticle
Barcode Reader configuration at IRL.	BCR camera absent at IRL.
2D Barcode Reader	Absent
Method for alignment of the laser beam	Align beam by optimizing pupil telecentricity params: LUBB
Beam Control	Closed loop
Beam Measuring Unit Type	Type 1
Beam Shaping Module	No Beam Shaping Module present
Bubble Extraction Seal Setting	Bes boost 2
Metrology overlay setup method	Metrology overlay setup calibration to nominal
Describes at what plane the BMU measures	Correct for BMU below DOE1 level
Boost Exposure Routing Configuration	Default
Laser capability for retrieving High Bandwidth Data	Laser does not provide Bandwidth Data
Carrier Handler Type	Mark II 300 Foup
Computational ASCAL	Commercial cASCAL option disabled
Center pole location in the machine	Center pole is located in the center
Chuck 1 wafer size	300mm
Chuck 2 wafer size	300mm
Chuck Dedication	Enhanced
CDC	Enabled
Circuit Dependent FEC	Present
Clean Air Configuration	Others
Inlet restriction for clean air	Inlet restriction at right side
Clean Air Temperature Control	Driver and ACC
Clean Air Temperature Performance level	Level 2
Combined stage alignment	Enabled
Graphical Toolkit for MC/FC/TE Constants Editors	Motif toolkit
Choice of COWA1 vertical setpoint calculation	Wait for current wafer capture result for the calculation
CoWa2 vertical setpoint	Use Global Wafer Wedge result as CoWa2 vertical setpoint
SECS overlay corrections per exposure	Not allowed
Corr. Per Exposure Lot reporting includes ADELsbcoverlay.	Include the ADELsbcoverlay intrafield contribution.
Allow L1L7 Type 1 Optimization	Absent
Core switch hardware type	No core network switch hardware present
Control CS_event_check behavior	CS_event_check will block tools if active events exist
XT19x0 throughput performance enhancement package.	Not applicable
CT Miscellaneous Rack	Present
Data Trace Manager Toolkit	Motif toolkit
Baseliner diffraction based focus stability control	Baseliner diffraction based focus stability control enabled
Dedicated Stage Alignment	Disabled
Depolarizer type	no retarder but pce-depolarizer
Data Handling Host VP item	Data Handling Host is absent.
Hardware version of Data Handling Host	Absent
Diaphragm Limiter	Absent
Allow different Exp,TIS Align set	Absent
Diff pressure correction for IFM beams	Present
Possible triggers for disk cleaning	M-action can trigger disk cleaning
Depth of Focus enhancement with adjustable laser bandwidth	Laser bandwidth is not adjustable
Dosecontrol Hardware	DCB
DOSEMAPPER	Present
DOSE_MAPPER_1	Present
Double TIS scan	Disabled
DP Storage Backend	Use DDDB as storage backend
SPM Dual Speed Data Delay	Absent
DUV Lightsource Power Level	60.00 Watt
Dynamic Performance Calculation	Mark 2
E-chuck Flatness Qualification Test	Disabled
EDA Interface	Disabled
EDA Interface standard Freeze	Level I

Activate Edge Speed Limiter. Protected	Edge Speed Limiter Standard
EDO	Disabled
EFESE	Absent
Exchangeable Last Lens Element	Present
Embedded board diagnostic functionality	Disabled
Indicate which leveling spec shall be used.	The leveling spec is unknown.
Disable or enable the encryption of Recipes send to the Tool	Do not encrypt any recipes or layer files on Tool.
Energy Sensor	Star TechC
Enhanced exposures 1	Present
Enhanced Exposure Overlay	Full
Enhancements in Reticle Monitor	move feedback inspection overview
Exchangeable Pupil Lens Element	Present
Exchangeable Pupil Lens Element	EPLE Type INACTIVE
ER hotlist promotion	Promotion to SECS with a generic EXID and ALID
ESC wait and repeat functionality	ESC wait and repeat functionality is not available
Energy sensor calibration type. Protected	Fast
ESO Manual Override	ESO Manual Override Disabled
Activate ESO MAX speed Allowed. Protected	ESO MAX Speed Allowed Disabled
Event Viewer Toolkit	Motif toolkit
EXE Architecture Revision	None
Enable ExpoFlex functionality	ExpoFlex is unavailable
Exposure routing throughput optimization for KrF	Exposure routing throughput optimization for KrF is disabled
Extended Lens Heating History (ELHH)	Enabled
Determination of NA ellipticity	Disabled
Extended Spot Sensor Matching	Present
Extended Zone Alignment	Disabled
Imaging Fading Control	Lens set-up only
Fast Avoidance Routing	Disabled
Fast VSA	Fast VSA is disabled
Modelling for MAXYS	Absent
Extended maximum for FILS Timeout.	Standard
Extended minimum for FILS Timeout.	Standard
To indicate which final xy spec shall be used.	The final xy spec is unknown.
To indicate which fine SDM spec shall be used.	The fine SDM spec is unknown.
Flexray illuminator	Flexray Absent
FlexRay Control Rack Configuration	Absent
FlexWave Mode for Production	NONE - FlexWave is not used for production
Flexible Productivity	Enhanced productivity mode disabled
Focus Data Collection	Present
Focus Monitoring	Present
FSM Flexibility package	Disabled
Allow wafer plane deviation check with Focus Monitoring	Disabled
Filtering of the SUSD correction.	Filtered SUSD correction is disabled.
Focal specification	Unknown
FQ configuration specs	Disabled FQ
Gas Control Unit Type	Ultra High Flow (UHF)
Green Laser Attenuation Feature	Not Allowed
Gridmapper	Enabled
switch for 3DOF / 6DOF HDM	HDM_TYPE_6DOF
High resolution System performance	Disabled
PEP High SLIP	PEP High SLIP is disabled
Option to apply the usage of HO marks in StageAlign	Use XPA marks in StageAlign.
Choice of horizontal stage align setpoint	Wait for vertical stage align result
Enable or disable image alignment fading correction	Disable image alignment fading correction
Intensity Calibration Per DOE	Enabled
Type of 1st general purpose amp	TAPA
Type of 5th general purpose amp	TAPA

XT REMA MPAC board type	MPAC type 1
Imaging Control Rack Configuration	IMCR
Enables system idle conditioning	System idle conditioning disabled
IFM Laser Configuration	AOM Recombo Laser
Ifm config at measure side.	8 axes
Interferometer axis version at exposure	3 plus 1 axis
Intrafield Higher Order Process Corrections Per Exposure	Intrafield HOPC per exposure is Disabled
enables ihopc per image per chuck	disables ihopc per image per chuck
ILIAS Fast Zernike concatenation	ILIAS Fast Zernike concatenation disabled
ILIAS lens setup	Absent
Number ofsupported fast Zernikes	ILIAS number of supported Zernikes 25
ILIAS number of supported Zernikes	ILIAS number of supported Zernikes 37
ILIAS Pupil measurement performance node	ILIAS Pupil measurement performance node 19
ILIAS Sensor Location	Both
ILIAS sensor type chuck 1	Hyper NA MK4
ILIAS sensor type chuck 2	Hyper NA MK4
PUPILIAS matching in terms of sigma measurement	No matching
ILIAS Zernike measurement performance node	ILIAS Zernike measurement performance node 19
Striping correction ILIAS sensor	Enabled
Illumination modes	All illumination modes
Illuminator Machine Safety Hardware	PTI board
Illuminator Type	190
Illuminator platform	Aerial XP
Pupil qualification method	Geometric centre method
Image quality data path arch	Data path architecture A
Imaging Electronics Architecture	B Architecture
Imaging Generic Power Amplifier	Ten Axis Power Amplifier
Immersion	Present
Immersion style Final XY tools for Dry Systems	Disabled
Immersion hood heater configuration	Internal single segmented heater
Improved Contrast Control	Absent
Use global wafer shape instead of wedge in fallback fields	Disabled
Improved FSM algorithm. Part of FIP-1 commercial package.	Disabled
Improved Edge Field Leveling	Enabled
Field width optimised leveling	Disabled
Constrained fit	Disabled
Improved wafer reject mode	Disabled
Switch INFORMPRO2 Data Package reporting	InformPro2 is unavailable
Data collection not covered by FOCUS and OVERLAY	Enabled
Report if a Recipe was modified by remote Host or Operator.	Do not report how Recipe was changed.
Type of inline cleaning cabinet	ILCC absent
Intensity Calibration Type	Type 1
Light-source Intensity Protection Type	Type 1
Interferometer Electronics	Ifsr
Overlay Interfield Corrections	Disabled
Intrafield fingerprint correction.	Functionality is not present.
Intrafield Higher Order Process Corrections	Enabled
Intrafield Wafer Alignment	Disabled
Integrated Reticle Inspection System	PPD2 with IRIS5um functionality.
Integrated Reticle Library	IRL_XP XCDA PURGED functionality
Projection GPA Configuration Version	Version 2
Extend IRIS maximum particles scanned to 50000.	Present
Iris feature Scan	Present
IRL barcode reader type	1D barcode reader is present at IRL
Laminar Bottom Hood	Absent
Large Range Leveling	Disabled
Lot Alignment Report Encryption	Unencrypted

PVP for disabling the laser burst interaction functionality	Enabled
Laser Gas Life eXtension	Enable Laser Gas Life eXtension;
Layout Independent Leveling	Layout independent wafer leveling is not supported
Layout dependent corrections.	Layout dependent effects are not corrected.
LCI WaitWatcher plug-in	Absent
Lens Circuit Water Flow	High Immersion
LCW Circuit set-up	Pressure Version 1
Loadport barcode reader type	Original barcode reader at the loadports
LEC Rack in Electronic Architecture	Absent
Lens OverPressure Compensation	OverPressure Compensation Enabled
Lens Top Tool Connection	Lens Top Tool can not be mounted on top of the Lens
Lens Type	91
Levelling throughput improvement on measure side	Levelling throughput package A
Application Specific Lens Heating Calibration & Verification	Present
Lens Heating Feedback	Absent
Light-source Architecture	Laser
Light-source Type	Cymer Laser: XLA 460
Light-source Wave-length	193nm
Liquid Particle Counter Unit	No Liquid Particle Counter Unit installed
Dose System Performance Test for Lithoguide	Present
FOCAL Measurement for Lithoguide	Present
ILIAS Functionality For Lithoguide	Present
Lithoguide Imaging Recipes	Absent
ISIS Functionality For Lithoguide	Absent
Leveling Verification Test for Lithoguide	Present
XML output for LITHOGUIDE	Disabled
PUPIL Measurement For Lithoguide	Present
SAMOS Stray Light Test For Lithoguide	Present
LoCo C2C drift correction	Disabled
Scaling of Lot Correction field effects	Scaling of Lot Correction functionality is absent
AST offset usage during LOCO TIS	Disabled
Log missed translations	Disabled
To enable the closing wafer refresh functionality	Enabled
Lot Correction Sequence	Type D
Lot Overhead Reduction	LOR2
Lot Report Data Category	Enhanced Diagnostics
Air Gauge	Present
Type of Air Gauge	TYPE_1: Initial air gauge (-25.5mm)
Extended LS areas	Disabled
Type of LS capture	Stepping
Level sensor type	Visible Level Sensor
Level Sensor CPU configuration	Use board lf1
LS focus node	LS focus node 5
Type of level sensor gratings.	30um pitch grating for 16um LS Period
Level Sensor Light Source type	Halogen or Energetiq EQ-99
Point-to-Point LS Machine Matching	Disabled
LS_PEMM_CONFIG	Absent
Level Sensor Processing Rack	MPCR
LS spot coverage	Absent
Z-capture on low reflectivity wafers	Z-capture on low reflectivity wafers is disabled.
LVT modeling version.	LVT model version 1 is enabled.
Machine Architecture	XT Machine Architecture
Machine Location	Customer Site
Machine Specification	G Specification
Machine Type	1900
Unprepare fully preprocessed lot for M-actions	Disabled
MALE used in production.	MALE is disabled in production.

Enable the Maintenance Assistant	Disable Maintenance Assistant
Maximum numerical aperature (NA) allowed in Lot Production	level 0
Max alignment speed	Setting 2
Maximum Reticle ID Length	24 Characters
Maximum wafer size allowed on the system	Maximum wafer size 300 mm
mbds control	Present
MCH1 hardware version	No MCH1 hardware is present
Motor Circuit Water Flow	High Immersion
MDL Viewer	Site View
Type of MDRC used.	Not applicable.
Metroframe Temperature Performance level	Level 1
Metroframe type	TYPE_A
Metroframe Circuit Water Cabinet	Absent
Multi Functional Exchangeable Lens Element	Projection lens has no MF-EPLE
Pressure update rate for fringelength correction	Pressure update rate 2 or 4 Hz
Managed Switch 1 type	No MSW1 hardware present
Managed Switch 1 (MSW1) network configuration version	No managed switch 1 is configured in the AERC
Managed Switch 2 type	No MSW2 hardware present
Managed Switch 2 (MSW2) network configuration version	No Managed Switch 2 is configured
Managed Switch 3 type	No MSW3 hardware present
Managed Switch 4 type	No MSW4 hardware present
Managed Switch 5 type	No MSW5 hardware present
Managed Switch 6 type	No MSW6 hardware present
Multilingual UI	Absent
Multi Focal Imaging Mode	Not applicable
Multiple wafers on output path configuration	Only one wafer at a time on the output path possible
Improved Maintenance action scheduling.	Disabled
NA1 motor type	None
Athena Narrow Marks Twinscan	Present
NA Control Architecture	NA3 Half Bridge
NA Control Type	190
Is NA accuracy measurement allowed?	Enabled
Type of NEXZ actuator	NEXZ with 885nm range (NO3)
Differentiate between different HIB boards	Three HIB186 boards to determine the positions of the NeXZ
Net lot overhead optimization for exposure sequence	No optimization
Number of Active Elements	2
Number of Active Lens Elements	0
Number of Active Manipulator Elements	0
Number of Bi-directional Active Lens Elements	2
Number of bending points (mirrors).	Not applicable.
Number of Lens Z Manipulators Using Camdisk	0
Number of manipulable ELLE axes	6
Number of EXLE elements	1
Number of Half Dome Mirrors	2
Multifunctional Active Elements	0
Multifunction Active Lens Element	0
Number of Lens NEXZ Manipulators	6
Number of Rxm	6
Number of Rym	6
Number of Semi-Active X-Y Lens Manipulators	6
Number of Z Lens Manipulators	6
Number of pre-amps available per Z-manipulator	0
NXE Arch. revision	no revision
NXT Arch. revision	no revision
OADB Improved Dynamic Range	Enabled
DoseSystemPerformanceTest sequence	Test sequence 1
Off-axis slit	Projection lens has an off-axis slit.

Physical location of OIU.	Not applicable.
BaseLiner Optima WEC/REC Control	BaseLiner Optima WEC/REC application is disabled.
Integrated Reticle Inspection System Configuration.	Enable creation of OSIRIS viewable files for PPD2 systems.
Overlay Data Collection	Overlay Data Collection enabled.
Parameter indicates how long overlay data will be stored.	Short retention period.
Overlay Node	Level 0
Overlay Node for Boost Mode Lot's	Level 133
Use the old at4.0.3 SPE sequence (ASF)	Do not overrule the SPE sequence
Piezo Active Lens Mounts	Digital MK-1
Controls parasitic stiffness type	Type 1, no spec selection
Location of PARIS sensor on chuck 1	No PARIS sensor on chuck 1
Location of PARIS sensor on chuck 2	No PARIS sensor on chuck 2
Type of PARIS sensor on chuck 1	No PARIS sensor on chuck 1
Type of PARIS sensor on chuck 2	No PARIS sensor on chuck 2
PCE Location	pce in APEX
Number of Motion Controllers	5 Motion Controllers present
Position Control Power Rack Configuration	TYPE_5: Stages Power Rack upto G-spec
Position Control Motion Control rack	MPCR
Process Dependent Gain Correction	Present
PDGC correction subrecipe deletion	Disable deletion of ASML created PDGCCorr subrecipes
PDOC correction subrecipe deletion	Disable deletion of ASML created PDOCCorr subrecipes
PED control mode	Absent
Reticle load protection for too wide/wrongly placed pellicle	Disabled
PEP Image Streaming	Present
Performance Enhancement Package	1
Machine Performance level	None
Particle Extraction Mass Flow Meter	Absent
The version indicates who implements the PFNI dose sequence	Metrology implements the PFNI dose sequence
Readout location of Pneumatic Facility Unit sensors	CT sensor board (CTS)
Conditionally reset the POB	Include POB in system reset
Polarization	Present
Polarized illumination amorph DOE.	Only unpolarized illumination.
Extended measurements after expose	Disabled
Type of projection multiplexer board	MUX type LAMB
Derived Lens Type for common metrology software	91
Proximity Matching	Present
Polarization Shaping Element Retractor	PSER hardware installed in the machine
PSE Location	pse in PSER
PSE type	XY polarization
PUPICOM	Present
PUPICOM Architecture	Multi Spoke
Set PUPICOM use	MULTIPLE_POSITIONS
Pupil forming optics	Zoom, axicon and DOE
Pupil measurements with ILIAS	Present
Purge Hoods configuration	Extremely Clean Dry Air only
Nitrogen Purge Utility Control	Absent
purging configuration	purging CONFIG 6
Rapid prototyping using Python to control the machine.	Disable rapid prototyping.
QXE Architecture Revision	No revision
QXT Architecture Revision	No revision
Reporting of K9/K10 coefficients from reticle alignment	RA_K9_K10_DATA_COLLECTION is Disabled
Enables RA Multiple Scans	Disable RA Multiple Scans
Reduced capture range for TIS scans	Enable reduced range TIS scan scenarios
Reticle alignment scenarios	XT reticle align scenarios
TIS plate usage in reticle align	RA always measures TIS1 and TIS2
Recipe Creator	Light
Reduce RS preptime for ILIAS scans.	Use default ILIAS preptime

Settle time reduction to improve the throughput	Reduced settle times
REMA architecture	XTREMA
ReMa mark	Mark1
Ability to use remote test service	Remote test service is disabled
Reorder Lot Service	Present
Reticle exchange type	Retex option: E
Reticle Align High Precision	Absent
Enhanced Throughput Reticle Alignment	Extended
Reticle Carrier Location	Left
Reticle Carrier Tag Reader	Present
Improved Reticle Control	Basic TOP-RC behavior
Reticle Heating Control	Reticle Heating Control for NEXZ elements in scanning mode
wildcard matching to reuse reticle heating TOPRC records	Reticle heating control calibration record reuse is disabled
Select Reticle Puffing Availability	Reticle Puff Not Available
Reticle Size	6 inch
Improvements for reticle handling	Enabled
Reticle shape correction	Enabled
Reticle streaming	Reticle Streaming enabled
Reticle streaming II	Disabled
Reticle Streaming 3	Reticle Streaming 3 Disabled
Reticle streaming lite	Disabled
Reticle Heating Control acceptance test: zero layer reticle	Use BP-XY-V2 or compatible reticle on RHC zero layer
Reticle Handler Machine Architecture	Reticle Handler is designed to handle reticles in air.
Reticle Streaming Options	Reticle Streaming 1
Reticle Handler type	RH Mark IV
Reticle Level Polarization Sensor	Present
Number of RMCS clients	No clients
PSE-type of PSE located in ROE (Asymmetrical or Symmetrical)	Not Applicable
Reticle Balance Mass 1 amp.	550V25A: PAAC XT rev3
Reticle Balance Mass 2 amp.	550V25A: PAAC XT rev3
Capacitive z-height sensor type.	Extended Z sensor board
Reticle Stage Chuck Type	TYPE_6: Two part chuck
Reticle Stage Chuck Type	Magn. Grav. Comp. Changed Lens Top
Zeroing type for Encoders Measurement System	Using reference marks on the encoder scales
Reticle Stage Lenscooler Box	Lenscooler Box with anti-aliasing Filter
Reticle Stage Long Stroke Config	TYPE_6:CoFe_18+magn.cooling,SIOB,int. vacuum supply,magn. GC
Reticle Stage Long Stroke Motor Type	Cobalt Ferro 18 teeth
Reticle Stage Long Stroke Y11 amp.	550V25A: PAAC XT rev3
Reticle Stage Long Stroke Y12 amp.	550V25A: PAAC XT rev3
Reticle Stage Long Stroke Y13 amp.	Don't care
Reticle Stage Long Stroke Y21 amp.	550V25A: PAAC XT rev3
Reticle Stage Long Stroke Y22 amp.	550V25A: PAAC XT rev3
Reticle Stage Long Stroke Y23 amp.	Don't care
Motion profile for specific applications.	Use default configuration profile.
Nitrogen purging of Reticle Stage	RS is not purged
RS Object Field	Shifted 19x0
Reticle stage parking	Disabled
Reticle Stage purged mini environment	Present
Reticle Stage Measurement System on Scan	Heidenhain Encoders
Reticle Stage Short Stroke X amp.	PADC 52V/6A
Reticle Stage Short Stroke Y11 amp.	PADC 130V/24A
Reticle Stage Short Stroke Y12 amp.	PADC 130V/24A
Reticle Stage Short Stroke Y21 amp.	PADC 130V/24A
Reticle Stage Short Stroke Y22 amp.	PADC 130V/24A
Reticle Stage Short Stroke Z1 amp.	PADC 52V/6A
Reticle Stage Short Stroke Z2 amp.	PADC 52V/6A
Reticle Stage Short Stroke Z3 amp.	PADC 52V/6A

Reticle Stage Short Stroke Z4 amp.	Don't care
Router hardware type	No router hardware present
Reticle Temperature Sensor	RTS hardware is present
Is this a machine with a safety PLC.	Safety PLC is not available in the Twinscan.
Stage Alignment Filter	Absent
Stage align just before FIWA	Disabled
Enables SA Multiple Scans	Disable SA Multiple Scans
Stage Alignment Phases	Fine stage alignment
TIS plate usage in stage align	SA always measures TIS1 and TIS2
Pattern Matcher	Present
Pattern Matcher Full Chip	Absent
Scanning Energy Sensor Calibration	Scanning Energy Sensor Calibration
Scan Direction Matching	Disable Scan direction matching
Hardware version of Scanner Control Host	x86 mk2.x SSD
To indicate which SDM spec shall be used.	The SDM spec is unknown.
SDM test on machines without SAXY elements	Disabled
Equipment Constants via SECS interface	Enabled
Stages servo performance	Default servo performance
Setup sensor board version	Setup SSD version LSDB
Type of measurement carried out as SFPM measurement	The SFPM measurement is disabled
Indicates whether the SFPM model is enabled	The SFPM model is disabled
Shot Data Collection	Present
Use Sigma Calibration	apply Sigma Calibration
Use Sigma WIP Preserving Offsets	no Sigma WIP Preserving Offsets
Skip MHV2 scans in Reticle Align for BOOST Mode	Skip MHV2 scans in Boost mode
Enable or disable SLIP / Intensity protection	SLIP / Intensity protection is disabled
Small Alignment Marks Support	No Small Marks
Insert a delay time before starting a Lot (lens heating).	Disabled
Enable to support SMASH XY mark types.	SMASH XY marks are not supported.
Specifies which mark types are supported	ASML marks only
SMASH Reuse Capture Information in Stage Alignment	Coarse capture is done and reused per wafer.
Smooth Field Uniformity	Absent
Activate 2Dspg for long y-moves only. Protected	2Dspg for long y-moves only disabled
Weighing of 2-Sided X-interferometers	Variable interferometer weight factors
2 Sided IFM-beams for WS-X (expose)	Available for production
2 Sided IFM-beams for WS-X (measure)	Available for production
SPM temp correction for lens axis	Disabled
SPM WS Optimized Sampling	Disable optimized phase capturing
SPM WS Optimized Sampling TOP4	Disable optimized phase capturing
WS Zeroing using Absolute Phase Capturing	Off
SPM WS YRY mirror map	Applied to ryz
SPM reference axis at measure side (XT ARA)	No reference axis at measure side available
Use Ryx or Ryz for the x Abbe correction	Use Ryx for the x Abbe correction
Spot Sensor Chuck 1	VLOC
Spot Sensor Chuck 2	VLOC
Position of Spot Sensor on Chuck 1	Spot Sensor Position on Chuck 1 layout 3
Position of Spot Sensor on Chuck 2	Spot Sensor Position on Chuck 2 layout 3
Spot Sensor Reticle Stage	Present
Changed Short Stroke diff XY controller	Disabled
Angular sensitivity corrections of Spot Sensor on Chuck 1	Enabled
Spotsensor chuck 1 surface coating	SiO2
Angular sensitivity corrections of Spot Sensor on Chuck 2	Enabled
Spotsensor chuck 2 surface coating	SiO2
Stages Sample Rate	5.0 kHz
Wafer stage technology	Wafer stage H-drive
Stand-alone Workstation	False
System Startup/Shutdown screen type	Select Motif screen

Version of RS/WS IO library	Version 2
Interfield Scan Up Scan Down focus correction	SUSD enabled model type 1
Swap bridge 1 type	No swap bridge available
Swap bridge 2 type	No swap bridge available
LAR event log pollution reduction	Disable LAR event log pollution reduction
Use improved setpoint calculations for shifted images	Improved setpoint calculations are ENABLED
SASO robustness	Disable SASO robustness
Enable the SMASH FFT fit algorithm, including BGRM support.	Disable the SMASH FFT fit algorithm for periodic scan types.
Adjust LHV oscillation threshold of the green laser	Disable decreased green laser oscillation threshold
Single set of MCs for normal and Gridmapper expose scans	mapping disabled;
Enable/Disable LoS2SS error FF on measure side	LoS2SS error FF will be disabled regardless of MCs
Fast Wobble	Disabled
Use TIS1-TIS2 Reticle Alignment scenario for K-spec	TIS1-TIS2 Reticle Alignment scenario for K-spec is DISABLED
Delay ret move from RS during idle cond, m-act and CPDs	Delay reticle move requests from or to stage
Set the Mechanical Prediction Model for TOP-RC	Use New Mechanical Prediction Model (2) for TOP-RC
Improved robustness DPCM fit	Disable improved robustness DPCM fit
Improved CDFEC/FWOL application on non-yielding fields	Disabled
To switch OFF D2x and D2y corrections for LoCoE and 860lens	D2x and D2y corrections for LOCO E and 860 lens are ON
To switch ON use of V1 or V2 BA-XY reticle type	BA-XY reticle type is V1
To enable large range leveling improved PDGC calibration.	Improved large range PDGC disabled
Symmetrical Reticle Alignment	Enabled
Save throughput data to the disk	Disabled
Test Table	Absent
Test table architecture	Aerial XP
Test Table Z Axis	Worm Wheel
TFH Mode	Not Applicable
THFFC FDE model lens dependent	Enabled
Layout Version Number TIS Plate 1 on Chuck 1	TIS Plate 1 Layout Version 5
Layout Version Number TIS Plate 1 on Chuck 2	TIS Plate 1 Layout Version 5
Layout Version Number TIS Plate 2 on Chuck 1	TIS Plate 2 Layout Version 5
Layout Version Number TIS Plate 2 on Chuck 2	TIS Plate 2 Layout Version 5
Provides improved TIS CPD when enabled.	Provides improved TIS CPD for diagnostics only
TIS diffuser	TIS diffuser present
Usage of Energy Sensor data by TIS	Enabled
Layout Version Number TIS Fiducial	TIS Fiducial Layout Version 1
TIS_ITOP	Enabled
Layout Usage TIS Sensor	DUV TIS Sensor
TIS overlay and TPT node	TIS Overlay and Throughput Performance Node 19A
TIS Power switching	Disabled
Pupil TIS angular sensitivity calibration and correction	TIS Pupil Measurement will not be improved
TIS trigger mechanism	Use internal trigger mechanism
Usage of wavelength data by TIS	Enabled
Editable M-action queues	Editable M-action queues enabled
TOP HD	Present
Track Pre-warning signal (APR)	APR disabled
2D clamping specification	Unknown
2D grid correction	Enabled
UNICOM	Present
UNICOM Architecture	58 Motors
Unicom move check	Unicom move check enabled
Set UNICOM use	MULTIPLE_POSITIONS
Uniformity Improvement Package	Present
Universal Prealignment	Disabled
Is the UPS Ethernet connected to the Twinscan.	UPS is not connected to the Twinscan.

Ultra Pure Water flow controller (WICC)	Entegris NT Flow Controller
UPW Unit	Type A or type B UPW Unit installed
Use validity ranges around UIP data when Enabled.	Use exact matching for UIP data
Extended Range Leveling for UVLS	Default
Type of UV Level Sensor	Visible Level Sensor
Dose evaluation functionality for UV systems	Dose Evaluation for UV systems disabled
Dose Intensity Optimization	Disable Dose Intensity Optimization;
Online Lamp Peak	Disable Online Lamp Peak;
PEP-ADC Intensity	Disable PEP-ADC Intensity;
UV Shutter version	UV Shutter version 1
Measure and model strategy for vertical stage align	VSA and advanced XVSA
Reset type for VME racks	Serial reset
Wafer Switch	Absent
Wafers per Carrier	25
Choice of wafer capture position	Perform wafer capture at SOSI scan-in position
Wafer Carrier Location	Left
Wafer Id Reader	Absent
Overlay Wafer Level Corrections	Disabled
Wafer Mark Sensor	Absent
Wafer Shape Handling	Default
Wafer Size	300mm
Wafer Thickness	Range 1
Wafer Track	Present
Wafer type used in the machine	300 mm - SEMI Notch
Warped wafer shape support	Disabled
Wavelength Adjustable	Adjustable
Wavelength range of the light source	Obsolete, temporary for migration
Reporting standard for no-value wafer align data	No-value is represented by zero
Apply clamping grid correction during wafer align	enabled;
WES 2000M hardware presence	Absent
Wet Chuck Ex. while stay hovering (Chuck1=Exp,Chuck2=Mea)	Not Applicable
Wet Chuck Ex. while stay hovering (Chuck1=Mea,Chuck2=Exp)	Not Applicable
WH temperature conditioning type	Slow performance type used for XTIII and below.
Wafer-Handler Air-Extraction presence	WH Air-Extraction hardware is absent
Reduce wafer-load-offset tolerance of centring unit to 25 um	Standard
200mm wafer cassette.	FA192 25-slots
Wafer Handling Docking Plate	WH Docking Plate Extra Low Height
WH Dock spring leaf cam typ	Hard
Docking wheels at WH unload	Absent
Wafer Handling Drying Unit	WH Drying Unit Absent
Load Robot Internal Docking	WH LR Without Damping
Wafer Handling Load Robot Type	Scara Arm, 40 mm Z stroke
Load Robot Wrist Assy Type	WH LR Wrist Long Tension Rod
extended docking interface at Prealigner	ECC_0MM
Wafer Handler Pre-aligner Type	Pre-aligner with air-bearing table
Wafer Handler Productivity	Wafer Handler Productivity Level 1
Wafer Handling Pneumatics	Standard
Robot position adjustment	DISABLED
WH Robot Power Amplifier	CPM 20
Wafer Handling Store Unit Type	WH Store Unit 3 Slotted
Wafer Handler wrt BF Shifted in Z	Not Shifted
Wafer Handling TSU	WH TSU Heater Absent
Wafer Handling Unload Robot Type	Scara Arm, 40 mm Z stroke
Unload Robot Wrist Assy Type	WH UR Wrist Long Tension Rod
Wafer Handling Track Input	WH Wafer Track Input Via PU
Wet Imaging Control Cabinet	Type B
Wet Imaging Control Rack	WICR-i4 or WICR-i5

Wide Pellicle Detection	Absent
Wide Pellicle Detection Type	DISABLED
Availability of WID readout functionality	WID readout functionality absent
WS servo error is fed to RS for better combined performance	disabled
Turns on second waferstage host in atca rack	WS2 host is absent, and CSGR must not try to boot it
Turns on third waferstage host in AMCR rack	WS3 host is absent, and CSGR must not try to boot it
WS 14db controller.	WS 14db controller DISABLED.
WS Balance Mass	Stainless Steel
Wafer Stage Balance Mass 11 amp.	Don't care
Wafer Stage Balance Mass 12 amp.	Don't care
Wafer Stage Balance Mass 21 amp.	Don't care
Wafer Stage Balance Mass 22 amp.	Don't care
Type of Clamp Flow Unit installed for Wafer Stage	CFU mark 5 immersion
Type of wafertable on chuck 1 for immersion machine	SiSiC version 5.1
Type of wafertable on chuck 2 for immersion machine	SiSiC version 5.1
Specifies chuck1 config	Immersion mark 3
Specifies chuck1 layout relev. for Immersion	TYPE_2:t.b.d.
Specifies chuck1 version	Version 2
Specifies chuck2 config	Immersion mark 3
Specifies chuck2 layout relev. for Immersion	TYPE_2:t.b.d.
Specifies chuck2 version	Version 2
Closing disk type	SiC closing present
Wafer Stage Configuration	Wafer Stage type 4 configuration
Active wafer release for dry WS	False
Continuous clampable wafer table for dry WS	Absent
Type of e-pins calibration for Wafer Stage	1DOF (z only)
Type of E-pin tips installed for Wafer Stage	Stiff E-pin tips
Wafer Stage Expose Scan Strategy	Default
Wafer Stage Fast Stiff X Move Electronics	Present
Enables idle condition chuck swap	Wafer Stage Idle conditioning for immersion disabled
Immersion Hood SubSub version	Not Applicable
Immersion Hood Sub version	Sub-Version 0
WS Immersion Hood Only Testrig	Absent
Imaging performance package	Standard imaging performance settings for non-8xy
Type of immersion hood for immersion	Actuator Fixed Height
Immersion Hood version	Version 4
WS Immersion wafer table thermal control package	Six segmented BES heater and cold-end wafer table heater
WS Immersion throughput package	Tiger mode chuck swap closing disc exchange
WS improved step/scan behaviour.	Standard step/scan behaviour
Wafer Stage Coarse Wafer Align Improvement	None
Wafer Stage Long Stroke E CS amp.	550V25A: PAAC XT rev3
Wafer Stage Long Stroke E X amp.	550V25A: PAAC XT rev3
Wafer Stage Long Stroke E Y1 amp.	550V25A: PAAC XT rev3
Wafer Stage Long Stroke E Y2 amp.	550V25A: PAAC XT rev3
Wafer Stage Long Stroke M CS amp.	550V25A: PAAC XT rev3
Wafer Stage Long Stroke M X amp.	550V25A: PAAC XT rev3
Wafer Stage Long Stroke M Y1 amp.	550V25A: PAAC XT rev3
Wafer Stage Long Stroke M Y2 amp.	550V25A: PAAC XT rev3
Long Stroke Sliding Mode Controller	Disabled
Wafer Stage Measurement System	Agilent interferometers
Wafer Stage Mirror Block Down Electronics	Absent
Move profile parameter configuration chuck 1	Not specified
Move profile parameter configuration chuck 2	Not specified
Wafer Stage Overlay Diagnostics	Disabled
Use a servo setting set	Default servo setting
Version of WS SIOB board installed	SIOB2 installed
Wafer Stage Short Stroke 1 XY1 amp.	PADC 130V/24A

Wafer Stage Short Stroke 1 XY2 amp.	PADC 130V/24A
Wafer Stage Short Stroke 1 XY3 amp.	PADC 130V/24A
Wafer Stage Short Stroke 1 Z1 amp.	PADC 52V/6A
Wafer Stage Short Stroke 1 Z2 amp.	PADC 52V/6A
Wafer Stage Short Stroke 1 Z3 amp.	PADC 52V/6A
Wafer Stage Short Stroke 2 XY1 amp.	PADC 130V/24A
Wafer Stage Short Stroke 2 XY2 amp.	PADC 130V/24A
Wafer Stage Short Stroke 2 XY3 amp.	PADC 130V/24A
Wafer Stage Short Stroke 2 Z1 amp.	PADC 52V/6A
Wafer Stage Short Stroke 2 Z2 amp.	PADC 52V/6A
Wafer Stage Short Stroke 2 Z3 amp.	PADC 52V/6A
Stressless wafer load for WS	Version 2
Wafer Stage Dedicated Hardware Configuration	None
Relative direction of ws to rs on the X axis	Same
Wafer Stage Type	Dual Chuck
WS prediction of wafer exchange timing	Default
Allowed wafer load controller level	Level 2
WS Wafer Align Scans	Default
Power supply type used for the wafer table BES heater.	Not applicable
In situ Wafer Table Stone Cleaning	Present
In situ Wafer Table Stone Cleaning Hardware Version	Stone 2
WVAC Unit	Type A WVAC Unit installed
Wafer z-map type.	Type 1: Pre-calculated setpoints from GLC
Extreme Clean Humiditied Air	Present
XML Lot Report Content Level	Basic
XT Architecture Revision	Rev3
To indicate which overlay spec shall be used.	The overlay spec is unknown.
2D exposure specification	Unknown
To indicate which distortion spec shall be used.	The overlay spec is unknown.
To indicate which data delay spec shall be used.	The data delay spec is unknown.
To indicate which repeatability spec shall be used.	The overlay spec is unknown.
Indicates which overlay spec is used	The overlay spec is set to SPEC_1
ZERO Fiducial	ILIAS MK4
Zoom Axicon Architecture	ZZA
Zoom Axicon Type	190